





### 240V P-CHANNEL ENHANCEMENT MODE VERTICAL DMOS FET

### **Features**

- BV<sub>DSS</sub> > -240V
- $R_{DS(on)} \le 8.8\Omega @ V_{GS} = -3.5V$
- Low threshold and Fast switching
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP capable (Note 4)

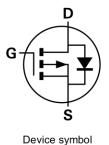
### **Mechanical Data**

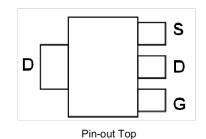
- Case: SOT89
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish @3
- Weight: 0.052 grams (approximate)

### Application

- · Electronic hook switches
- Telecoms and Battery powered equipment







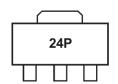
Ordering Information (Notes 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZVP4424ZTA	AEC-Q101	24P	7	12	1,000
ZVP4424ZQTA	Automotive	24P	7	12	1,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally
  the same, except where specified.
- 5. For packaging details, go to our website at http://www.diodes.com.

## **Marking Information**



24P = Product type Marking Code



## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	-240	V
Gate-Source Voltage	$V_{GSS}$	±40	V
Continuous Drain Current	Ι <sub>D</sub>	-200	mA
Pulsed Drain Current (Note 8)	I <sub>DM</sub>	-1.0	A

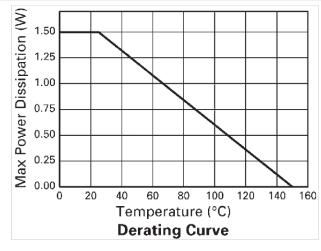
## Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

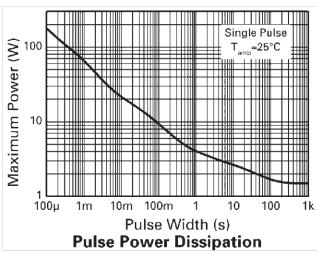
Characteristic	Symbol	Value	Unit	
Power Dissipation	(Note 6)	D_	1.5	W
Power Dissipation	(Note 7)	- P <sub>D</sub>	2.6	W
Thermal Resistance, Junction to Ambient	(Note 6)	В.	83.3	°C/W
Thermal Resistance, Junction to Ambient	(Note 7)	$R_{\theta JA}$	47.4	°C/W
Thermal Resistance, Junction to Leads (Note 9)		R <sub>θJL</sub>	3.64	°C/W
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

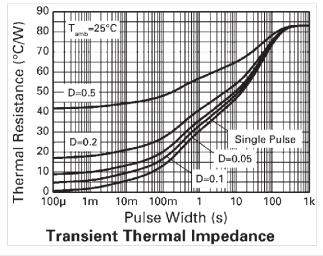
Notes:

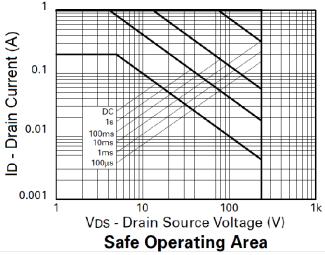
- 6. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
- 7. For a device surface mounted on FR4 PCB measured at t ≤ 10 sec.
   8. Repetitive rating 25mm x 25mm FR4 PCB, D = 0.02, pulse width 300µs pulse width limited by maximum junction temperature.
- 9. Thermal resistance from junction to solder-point (at the end of the drain lead).

### **Thermal Characteristics**













# Electrical Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-240		_	V	$I_D = -1 \text{mA}, V_{GS} = 0 \text{V}$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-10	μА	V <sub>DS</sub> = -240V, V <sub>GS</sub> = 0V
Zelo Gate voltage Dialii Current				-100	μΑ	V <sub>DS</sub> = -190V, V <sub>GS</sub> = 0V, T <sub>A</sub> = +125°C
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 40V$ , $V_{DS} = 0V$
ON CHARACTERISTICS	ON CHARACTERISTICS					
On state Drain Current (Note 10)	I <sub>D(on)</sub>	-0.75	-1.0	_	Α	V <sub>DS</sub> = -10V, V <sub>GS</sub> = -10V
Gate Threshold Voltage	V <sub>GS(th)</sub>	-0.7	-1.4	-2.0	V	$I_D = -1 \text{mA}, V_{DS} = V_{GS}$
Static Drain-Source On-Resistance (Note 10)	R <sub>DS(on)</sub>	_	7.1	9	Ω	$V_{GS} = -10V, I_D = -200mA$
Static Drain-Source On-Resistance (Note 10)			8.8	11		$V_{GS} = -3.5V, I_D = -100mA$
Forward Transconductance (Notes 10 & 12)	g <sub>fs</sub>	125	_	_	mS	$V_{DS} = -10V, I_{D} = -200 \text{mA}$
DYNAMIC CHARACTERISTICS (Note 12)						
Input Capacitance	C <sub>iss</sub>	_	100	200		V <sub>DS</sub> = -25V, V <sub>GS</sub> = 0V f = 1.0MHz
Output Capacitance	Coss	_	18	25	рF	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	5	15		
Turn-On Delay Time (Note 11)	t <sub>d(on)</sub>	_	8	15		
Rise Time (Note 11)	t <sub>f</sub>	_	8	15		$V_{DD} = -50V, I_{D} = -250mA$
Turn-Off Delay Time (Note 11)	t <sub>d(off)</sub>	_	26	40	ns	V <sub>GEN</sub> = -10V
Fall Time (Note 11)	t <sub>f</sub>		20	30	<u> </u>	

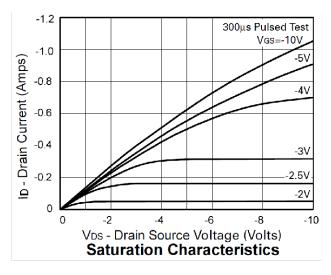
Notes:

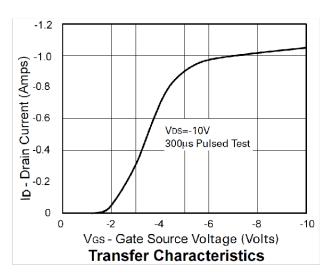
- 10. Measured under pulsed conditions. Pulse width =  $300\mu s$ . Duty cycle  $\leq 2\%$ . 11. Switching characteristics are independent of operating junction temperature. 12. For design aid only, not subject to production testing.

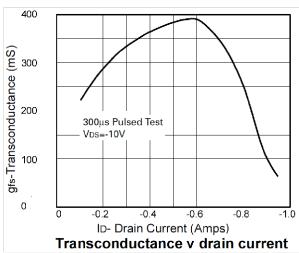


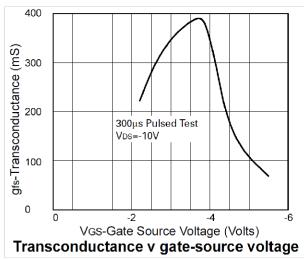


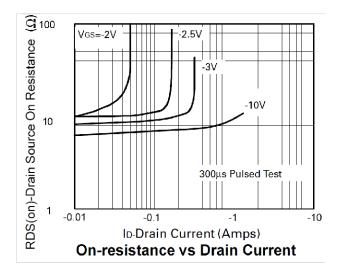
## **Typical Characteristics**

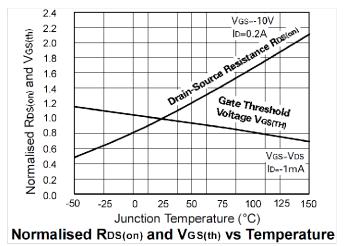










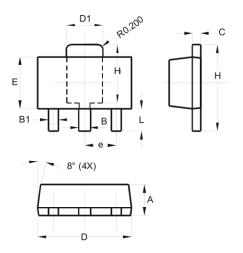






# **Package Outline Dimensions**

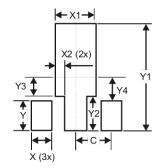
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT89				
Dim	Min	Max		
Α	1.40	1.60		
В	0.44	0.62		
B1	0.35	0.54		
С	0.35	0.44		
D	4.40	4.60		
D1	1.62	1.83		
E	2.29	2.60		
е	1.50 Typ			
Н	3.94	4.25		
H1	2.63	2.93		
L	0.89	1.20		
All Dimensions in mm				

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Х	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
С	1.500





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